

50

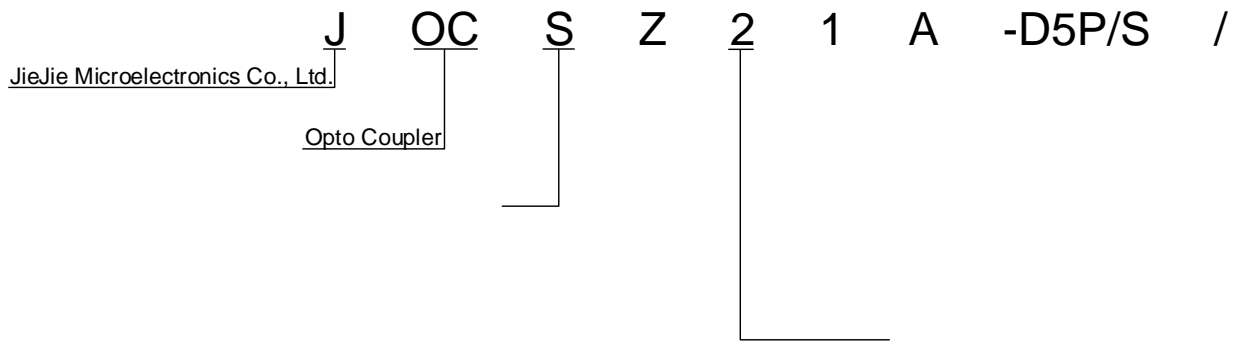
mA

1

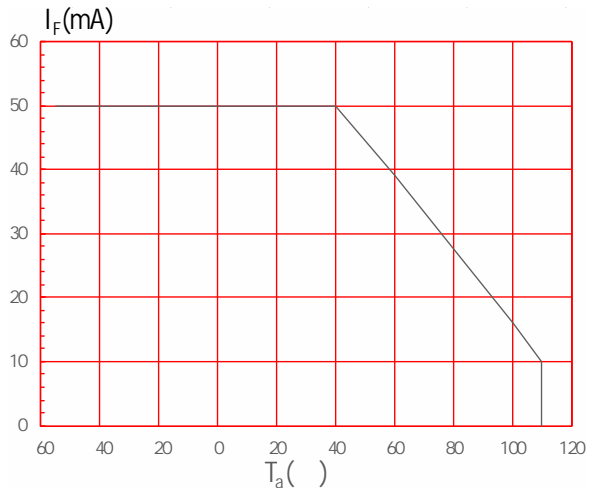
Input

Reverse Current

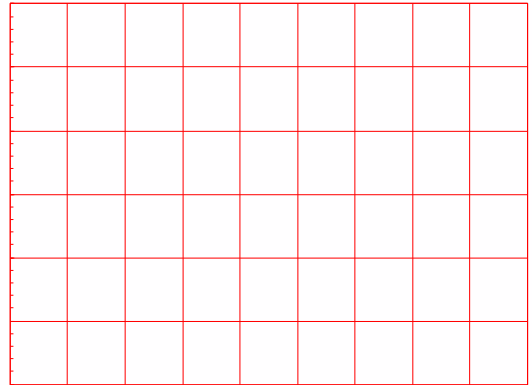
I



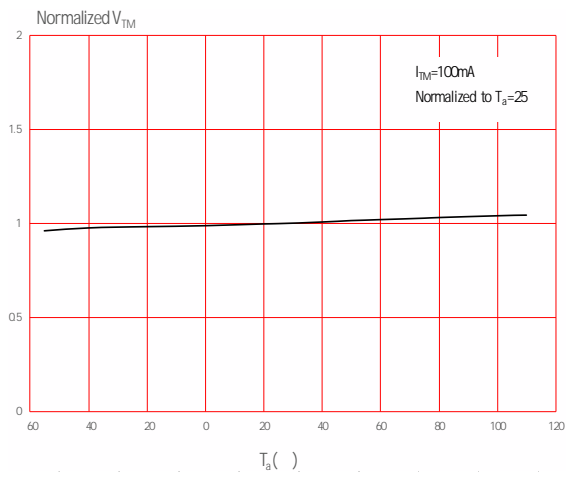
**FIG.1:** Max. Allowable LED Forward Current vs. Ambient Temperature



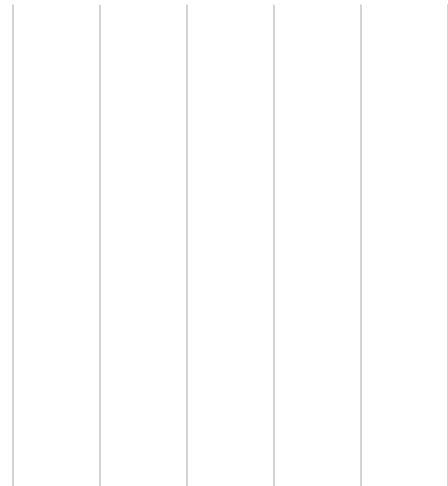
**FIG.2:** On-state Terminal Current vs. Ambient Temperature



**FIG.7:** Normalized On-state Terminal Voltage vs. Ambient Temperature

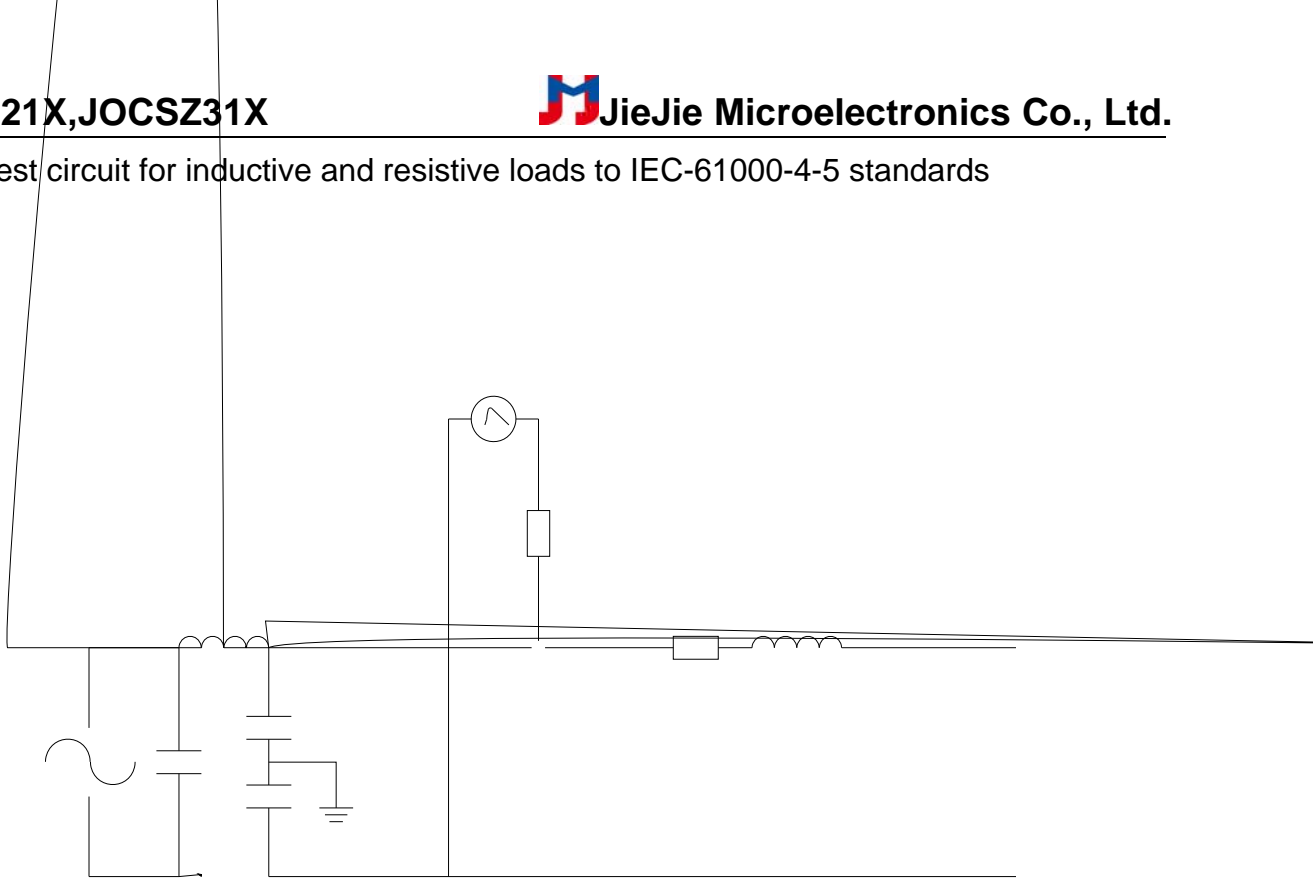


**FIG.8:** On-state Terminal Voltage vs. On-state Terminal Current



**JOC SZ21X, JOC SZ31X**

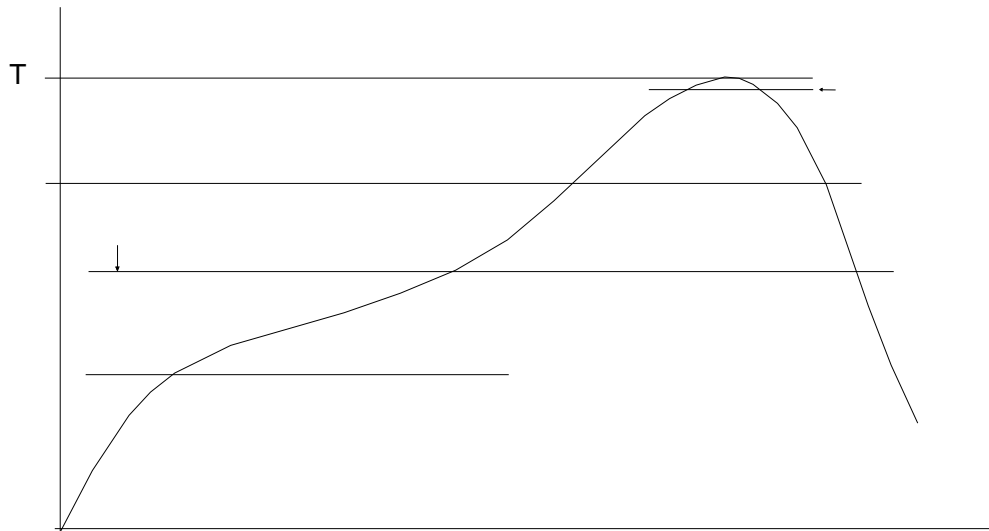
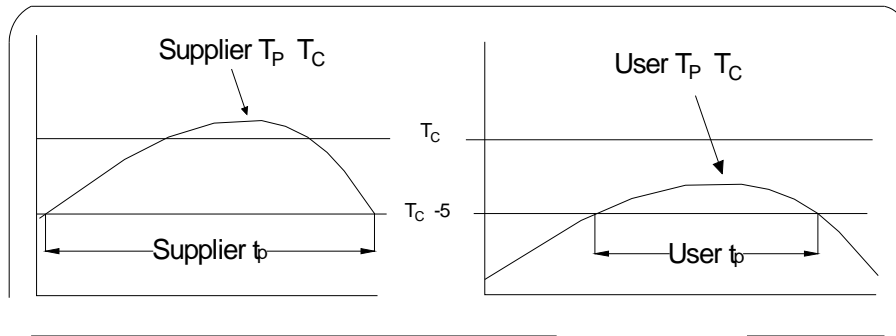
FIG.16: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards

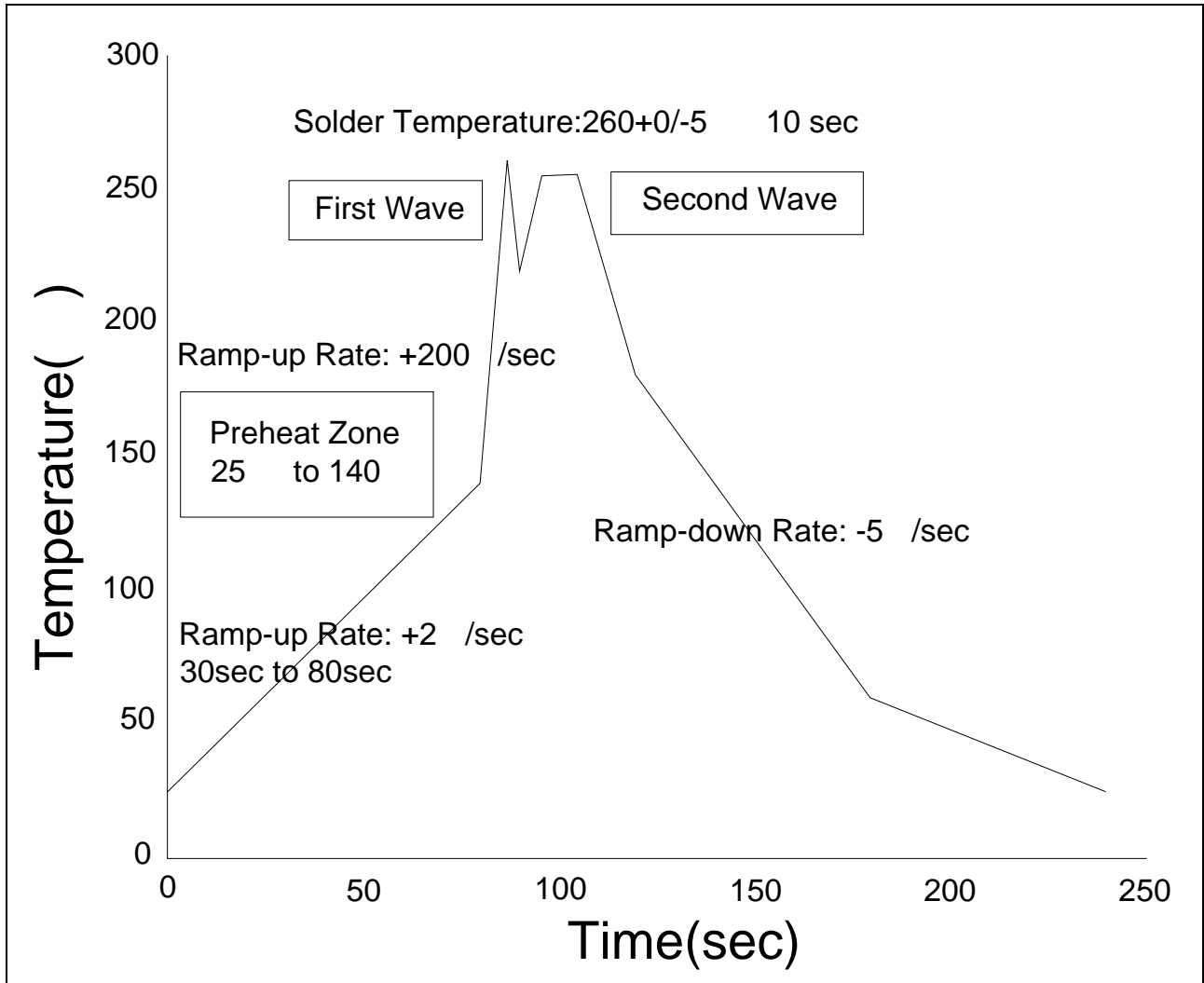


Option SMD Type:

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	9.50		10.50	0.375		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110







Soldering Temperature	$360 \pm 5$
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage Humidity: <60%;  
MSL level: MSL 1

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